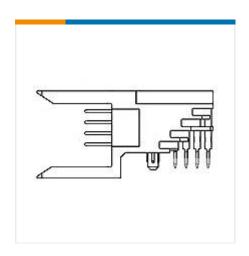


BOARD-TO-BOARD HEADERS & RECEPTACLES



✓ Active

TE CONNECTIVITY (TE) 2MMFB,IS,ASY,048,SIG,HDR,SL

Z-PACK | Future Bus+

5223513-2

TE Internal Number: 5223513-2

EU RoHS Compliant EU ELV Compliant

Connector Style Plug

Number of Positions 48

Centerline (Pitch) 2 mm [.079 in]

Packaging Method Tube

Contact Mating Area Plating Material Gold over Palladium Nickel



PRODUCT DRAWING

English



★ 3D PDF

DOCUMENTATION

Product Drawings

ASSEMBLY, PIN, SIGNAL, RIGHT ANGLE, 4 ROW, Z-PACK 2mm FB

PDF (TIFF AVAILABLE)

English

CAD Files

3D PDF

PDF

3D

Customer View Model

2D_DXF.ZIP

English

Customer View Model 3D_IGS.ZIP **English Customer View Model** 3D_STP.ZIP **English Product Specifications Application Specification Z-PACK 2 Mm FB (Futurebus+) Receptacle And Pin Header Connectors** PDF **English Product Specification** Connector, Z-PACK*, 2 Mm FB, Signal And Power PDF **English Qualification Test Report** Connector, Z-PACK, 2mm FB, Signal & Power TIF **English** Connector, Z-PACK, 2mm FB, Signal & Power PDF **English** Connector, Z-PACK, 2mm FB, Signal & Power PDF **Japanese** Product Environmental Compliance **TE Material Declaration** MD_5223513-2_030720171129_dmtec PDF **English FEATURES**

Please review product documents or contact us for the latest agency approval information.

Please Note: Use the Product Drawing for all design activity.

Product Type Features

Module Type Signal

Connector Style Plug

Connector & Contact Terminates To Printed Circuit Board

Post Type Solder Post

Row-to-Row Spacing 2 mm [.079 in]

PCB Mounting Orientation Right Angle

Connector Type Header

Boss Without

Product Type Connector

Configuration Features

Stackable No
Number of Positions 48
Number of Rows 4
Sequencing No
Number of Signal Positions 48

Electrical Characteristics

Dielectric Withstanding Voltage (VAC) 1000 Voltage (VAC) 30 Insulation Resistance (M Ω) 100 – 5000

Body Features

Post Plating Material Tin

Contact Features

Solder Tail Contact Plating Material Tin

Contact Mating Area Plating Material Gold over Palladium Nickel

Contact Mating Area Plating Thickness .08 µm [3.1496 µin]

Contact Current Rating (Max) (A) 3

Solder Tail Contact Plating Thickness 3.81 µm [149.9997 µin]

Contact Layout Matrix

Contact Base Material Phosphor Bronze

Contact Type Pin

Termination Features

Termination Method to PC Board Through Hole - Solder Termination Post Length 2.73 mm [.107 in]
Interface Type Futurebus+

Mechanical Attachment

Mating Alignment Type Polarization
PCB Mount Retention With
PCB Mount Alignment Type Locating Posts

Housing Features

Centerline (Pitch) 2 mm [.079 in]

Housing Material LCP (Liquid Crystal Polymer)

Housing Color Natural

Dimensions

Mating Post Length 5 mm [.197 in] Height 11.2 mm [.44016 in] Tail Length 2.73 mm [.107289 in] Width 16 mm [.622 in]

Usage Conditions

Operating Temperature Range (°C) -55 – 125

Operation/Application	
Assembly Process Feature Board Standoff	
Pick and Place Cover Without	
Packaging Features	
Packaging Method Tube	
Packaging Quantity 24	
PRODUCT COMPLIANCE	+
Statement of Compliance	
Statement of Compliance	
PDF	